

Rochester Electronics Manufactured Components

Rochester branded components are manufactured using either die/wafers purchased from the original suppliers or Rochester wafers recreated from the original IP. All recreations are done with the approval of the OCM.

Parts are tested using original factory test programs or Rochester developed test solutions to guarantee product meets or exceed the OCM data sheet.

Quality Overview

- ISO-9001
- AS9120 certification
- Qualified Manufacturers List (QML) MIL-PRF-35835
 - Class Q Military
 - Class V Space Level
- Qualified Suppliers List of Distributors (QSLD)
- Rochester is a critical supplier to DLA and meets all industry and DLA standards.

Rochester Electronics, LLC is committed to supplying products that satisfy customer expectations for quality and are equal to those originally supplied by industry manufacturers.

The original manufacturer's datasheet accompanying this document reflects the performance and specifications of the Rochester manufactured version of this device. Rochester Electronics guarantees the performance of its semiconductor products to the original OEM specifications. 'Typical' values are for reference purposes only. Certain minimum or maximum ratings may be based on product characterization, design, simulation, or sample testing.



January 2008

74AC373, 74ACT373 Octal Transparent Latch with 3-STATE Outputs

Features

- I_{CC} and I_{OZ} reduced by 50%
- Eight latches in a single package
- 3-STATE outputs for bus interfacing
- Outputs source/sink 24mA
- ACT373 has TTL-compatible inputs

General Description

The AC/ACT373 consists of eight latches with 3-STATE outputs for bus organized system applications. The flip-flops appear transparent to the data when Latch Enable (LE) is HIGH. When LE is LOW, the data that meets the setup time is latched. Data appears on the bus when the Output Enable (\overline{OE}) is LOW. When \overline{OE} is HIGH, the bus output is in the high impedance state.

Ordering Information

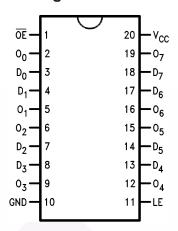
Order Number	Package Number	Package Description
74AC373SC	M20B	20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide
74AC373SJ	M20D	20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74AC373MTC	MTC20	20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
74AC373PC	N20A	20-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide
74ACT373SC	M20B	20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide
74ACT373SJ	M20D	20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide
74ACT373MSA	MSA20	20-Lead Shrink Small Outline Package (SSOP), JEDEC MO-150, 5.3mm Wide
74ACT373MTC	MTC20	20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide
74ACT373PC	N20A	20-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide

Device also available in Tape and Reel. Specify by appending suffix letter "X" to the ordering number.



All packages are lead free per JEDEC: J-STD-020B standard.

Connection Diagram



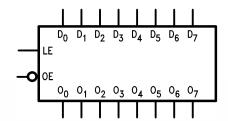
Pin Description

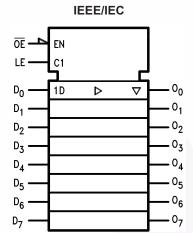
Pin Names	Description
D ₀ –D ₇	Data Inputs
LE	Latch Enable Input
OE	Output Enable Input
O ₀ -O ₇	3-STATE Latch Outputs

Functional Description

The AC/ACT373 contains eight D-type latches with 3-STATE standard outputs. When the Latch Enable (LE) input is HIGH, data on the D_n inputs enters the latches. In this condition the latches are transparent, i.e., a latch output will change state each time its D-type input changes. When LE is LOW, the latches store the information that was present on the D-type inputs a setup time preceding the HIGH-to-LOW transition of LE. The 3-STATE standard outputs are controlled by the Output Enable (\overline{OE}) input. When \overline{OE} is LOW, the standard outputs are in the 2-state mode. When \overline{OE} is HIGH, the standard outputs are in the high impedance mode but this does not interfere with entering new data into the latches.

Logic Symbols





Truth Table

	Inputs				
LE	ŌĒ	D _n	O _n		
X	Н	Х	Z		
Н	L	L	L		
Н	L	Н	Н		
L	L	Х	O ₀		

H = HIGH Voltage Level

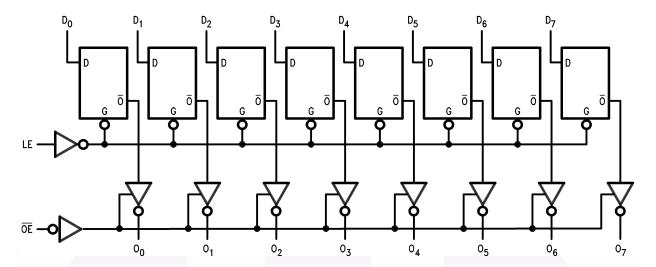
L = LOW Voltage Level

Z = High Impedance

X = Immaterial

 ${\rm O_0} = {\rm Previous} \; {\rm O_0} \; {\rm before} \; {\rm HIGH\text{-}to\text{-}LOW} \; {\rm transition} \; {\rm of} \; {\rm Latch} \; {\rm Enable} \;$

Logic Diagram



Please note that this diagram is provided only for the understanding of logic operations and should not be used to estimate propagation delays.

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Rating
V _{CC}	Supply Voltage	-0.5V to +7.0V
I _{IK}	DC Input Diode Current	
	$V_{I} = -0.5V$	-20mA
	$V_{I} = V_{CC} + 0.5$	+20mA
V _I	DC Input Voltage	-0.5V to V _{CC} + 0.5V
I _{OK}	DC Output Diode Current	
	$V_{O} = -0.5V$	-20mA
	$V_{O} = V_{CC} + 0.5V$	+20mA
V _O	DC Output Voltage	$-0.5V$ to $V_{CC} + 0.5V$
Io	DC Output Source or Sink Current	±50mA
I _{CC} or I _{GND}	DC V _{CC} or Ground Current per Output Pin	±50mA
T _{STG}	Storage Temperature	–65°C to +150°C
T_J	Junction Temperature	140°C

Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to absolute maximum ratings.

Symbol	Parameter	Rating
V _{CC}	Supply Voltage	
	AC	2.0V to 6.0V
	ACT	4.5V to 5.5V
V _I	Input Voltage	0V to V _{CC}
V _O	Output Voltage	0V to V _{CC}
T _A	Operating Temperature	-40°C to +85°C
ΔV / Δt	Minimum Input Edge Rate, AC Devices:	125mV/ns
	V_{IN} from 30% to 70% of V_{CC} , V_{CC} @ 3.3V, 4.5V, 5.5V	
ΔV / Δt	Minimum Input Edge Rate, ACT Devices:	125mV/ns
	$V_{\rm IN}$ from 0.8V to 2.0V, $V_{\rm CC}$ @ 4.5V, 5.5V	

DC Electrical Characteristics for AC

				T _A = -	+25°C	$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$	
Symbol	Parameter	V _{CC} (V)	Conditions	Тур.	G	uaranteed Limits	Units
V _{IH}	Minimum HIGH Level	3.0	$V_{OUT} = 0.1V$ or	1.5	2.1	2.1	V
	Input Voltage	4.5	V _{CC} – 0.1V	2.25	3.15	3.15	
		5.5		2.75	3.85	3.85	
V _{IL}	Maximum LOW Level	3.0	$V_{OUT} = 0.1V$ or	1.5	0.9	0.9	V
	Input Voltage	4.5	V _{CC} – 0.1V	2.25	1.35	1.35	
		5.5		2.75	1.65	1.65	
V _{OH}	Minimum HIGH Level	3.0	$I_{OUT} = -50\mu A$	2.99	2.9	2.9	V
	Output Voltage	4.5		4.49	4.4	4.4	
		5.5		5.49	5.4	5.4	
		3.0	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OH} = -12\text{mA}$		2.56	2.46	
		4.5	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OH} = -24\text{mA}$		3.86	3.76	
		5.5	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OH} = -24\text{mA}^{(1)}$		4.86	4.76	
V _{OL}	Maximum LOW Level	3.0	$I_{OUT} = 50\mu A$	0.002	0.1	0.1	V
	Output Voltage	4.5		0.001	0.1	0.1	
		5.5		0.001	0.1	0.1	
		3.0	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OL} = 12\text{mA}$		0.36	0.44	
		4.5	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OL} = 24\text{mA}$		0.36	0.44	
		5.5	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OL} = 24\text{mA}^{(1)}$		0.36	0.44	
I _{IN} ⁽²⁾	Maximum Input Leakage Current	5.5	$V_I = V_{CC}$, GND		±0.1	±1.0	μA
l _{OZ}	Maximum 3-STATE Leakage Current	5.5	$\begin{aligned} &V_{I}\left(OE\right)=V_{IL},V_{IH};\\ &V_{I}=V_{CC},GND;\\ &V_{O}=V_{CC},GND \end{aligned}$		±0.25	±2.5	μA
I _{OLD}	Minimum Dynamic	5.5	V _{OLD} = 1.65V Max.			75	mA
I _{OHD}	Output Current ⁽³⁾	5.5	V _{OHD} = 3.85V Min.			-75	mA
I _{CC} ⁽²⁾	Maximum Quiescent Supply Current	5.5	$V_{IN} = V_{CC}$ or GND		4.0	40.0	μA

Notes:

- 1. All outputs loaded; thresholds on input associated with output under test.
- 2. I_{IN} and I_{CC} @ 3.0V are guaranteed to be less than or equal to the respective limit @ 5.5V V_{CC} .
- 3. Maximum test duration 2.0ms, one output loaded at a time.

DC Electrical Characteristics for ACT

				T _A = -	+25°C	$T_A = -40^{\circ}C \text{ to } +85^{\circ}C$	
Symbol	Parameter	V _{CC} (V)	Conditions	Тур.	G	uaranteed Limits	Units
V _{IH}	Minimum HIGH Level	4.5	$V_{OUT} = 0.1V$ or	1.5	2.0	2.0	V
	Input Voltage	5.5	V _{CC} – 0.1V	1.5	2.0	2.0	
V _{IL}	Maximum LOW	4.5	$V_{OUT} = 0.1V$ or	1.5	0.8	0.8	V
	Level Input Voltage	5.5	V _{CC} – 0.1V	1.5	0.8	0.8	
V _{OH}	Minimum HIGH Level	4.5	$I_{OUT} = -50\mu A$	4.49	4.4	4.4	V
	Output Voltage	5.5		5.49	5.4	5.4	
		4.5	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OH} = -24\text{mA}$		3.86	3.76	
		5.5	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OH} = -24\text{mA}^{(4)}$		4.86	4.76	
V _{OL}	Maximum LOW	4.5	$I_{OUT} = 50\mu A$	0.001	0.1	0.1	V
	Level Output Voltage	5.5		0.001	0.1	0.1	
		4.5	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OL} = 24\text{mA}$		0.36	0.44	
		5.5	$V_{IN} = V_{IL} \text{ or } V_{IH},$ $I_{OL} = 24\text{mA}^{(4)}$		0.36	0.44	
I _{IN}	Maximum Input Leakage Current	5.5	$V_I = V_{CC}$, GND		±0.1	±1.0	μA
I _{OZ}	Maximum 3-STATE Leakage Current	5.5	$V_I = V_{IL}, V_{IH};$ $V_O = V_{CC}, GND$		±0.25	±2.5	μA
I _{CCT}	Maximum I _{CC} /Input	5.5	$V_I = V_{CC} - 2.1V$	0.6		1.5	mA
I _{OLD}	Minimum Dynamic	5.5	OLD			75	mA
I _{OHD}	Output Current ⁽⁵⁾	5.5				-75	mA
I _{CC}	Maximum Quiescent Supply Current	5.5	$V_{IN} = V_{CC}$ or GND		4.0	40.0	μA

Notes:

- 4. All outputs loaded; thresholds on input associated with output under test.
- 5. Maximum test duration 2.0ms, one output loaded at a time.

AC Electrical Characteristics for AC

				$T_A = +25^{\circ}C$, $C_L = 50pF$		$T_A = -40$ °C to +85°C, $C_L = 50$ pF		
Symbol	Parameter	$V_{CC}(V)^{(6)}$	Min.	Тур.	Max.	Min.	Max.	Units
t _{PLH}	Propagation Delay, D _n to O _n	3.3	1.5	10.0	13.5	1.5	15.0	ns
		5.0	1.5	7.0	9.5	1.5	10.5	
t _{PHL}	Propagation Delay, D _n to O _n	3.3	1.5	9.5	13.0	1.5	14.5	ns
		5.0	1.5	7.0	9.5	1.5	10.5	
t _{PLH}	Propagation Delay, LE to O _n	3.3	1.5	10.0	13.5	1.5	15.0	ns
		5.0	1.5	7.5	9.5	1.5	10.5	
t _{PHL}	Propagation Delay, LE to O _n	3.3	1.5	9.5	12.5	1.5	14.0	ns
		5.0	1.5	7.0	9.5	1.5	10.5	
t _{PZH}	Output Enable Time	3.3	1.5	9.0	11.5	1.0	13.0	ns
		5.0	1.5	7.0	8.5	1.0	9.5	
t _{PZL}	Output Enable Time	3.3	1.5	8.5	11.5	1.0	13.0	ns
		5.0	1.5	6.5	8.5	1.0	9.5	
t _{PHZ}	Output Disable Time	3.3	1.5	10.0	12.5	1.0	14.5	ns
		5.0	1.5	8.0	11.0	1.0	12.5	
t _{PLZ}	Output Disable Time	3.3	1.5	8.0	11.5	1.0	12.5	ns
		5.0	1.5	6.5	8.5	1.0	10.0	

Note:

6. Voltage range 3.3 is $3.3V \pm 0.3V$. Voltage range 5.0 is $5.0V \pm 0.5V$.

AC Operating Requirements for AC

			T _A = + C _L =	⊦25°C, 50pF	$T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C},$ $C_L = 50\text{pF}$	
Symbol	Parameter	$V_{CC}(V)^{(7)}$	Тур	Gua	ranteed Minimum	Units
t _S	Setup Time, HIGH or LOW, D _n to LE	3.3	3.5	5.5	6.0	ns
		5.0	2.0	4.0	4.5	
t _H	Hold Time, HIGH or LOW, D _n to LE	3.3	-3.0	1.0	1.0	ns
		5.0	-1.5	1.0	1.0	
t _W	LE Pulse Width, HIGH	3.3	4.0	5.5	6.0	ns
		5.0	2.0	4.0	4.5	

Note:

7. Voltage range 3.3 is 3.3V \pm 0.3V. Voltage range 5.0 is 5.0V \pm 0.5V.

AC Electrical Characteristics for ACT

			T _A = +25°C, C _L = 50pF		$T_A = -40$ °C to +85°C, $C_L = 50$ pF			
Symbol	Parameter	V _{CC} (V) ⁽⁸⁾	Min.	Тур.	Max.	Min.	Max.	Units
t _{PLH}	Propagation Delay, D _n to O _n	5.0	2.5	8.5	10.0	1.5	11.5	ns
t _{PHL}	Propagation Delay, D _n to O _n	5.0	2.0	8.0	10.0	1.5	11.5	ns
t _{PLH}	Propagation Delay, LE to O _n	5.0	2.5	8.5	11.0	2.0	11.5	ns
t _{PHL}	Propagation Delay, LE to O _n	5.0	2.0	8.0	10.0	1.5	11.5	ns
t _{PZH}	Output Enable Time	5.0	2.0	8.0	9.5	1.5	10.5	ns
t _{PZL}	Output Enable Time	5.0	2.0	7.5	9.0	1.5	10.5	ns
t _{PHZ}	Output Disable Time	5.0	2.5	9.0	11.0	2.5	12.5	ns
t _{PLZ}	Output Disable Time	5.0	1.5	7.5	8.5	1.0	10.0	ns

Note:

8. Voltage range 5.0 is $5.0V \pm 0.5V$.

AC Operating Requirements for ACT

			T _A = +	-25°C, 50pF	$T_A = -40^{\circ}\text{C to } +85^{\circ}\text{C},$ $C_L = 50\text{pF}$	
Symbol	Parameter	$V_{CC}(V)^{(9)}$	Тур	Gua	aranteed Minimum	Units
t _S	Setup Time, HIGH or LOW, D _n to LE	5.0	0.8	2.5	3.5	ns
t _H	Hold Time, HIGH or LOW, D _n to LE	5.0	0	0	1.0	ns
t _W	LE Pulse Width, HIGH	5.0	2.0	7.0	8.0	ns

Note:

9. Voltage range 5.0 is $5.0V \pm 0.5V$.

Capacitance

Symbol	Parameter	Conditions	Тур.	Units
C _{IN}	Input Capacitance	V _{CC} = OPEN	4.5	pF
C _{PD}	Power Dissipation Capacitance	V _{CC} = 5.0V	40.0	pF

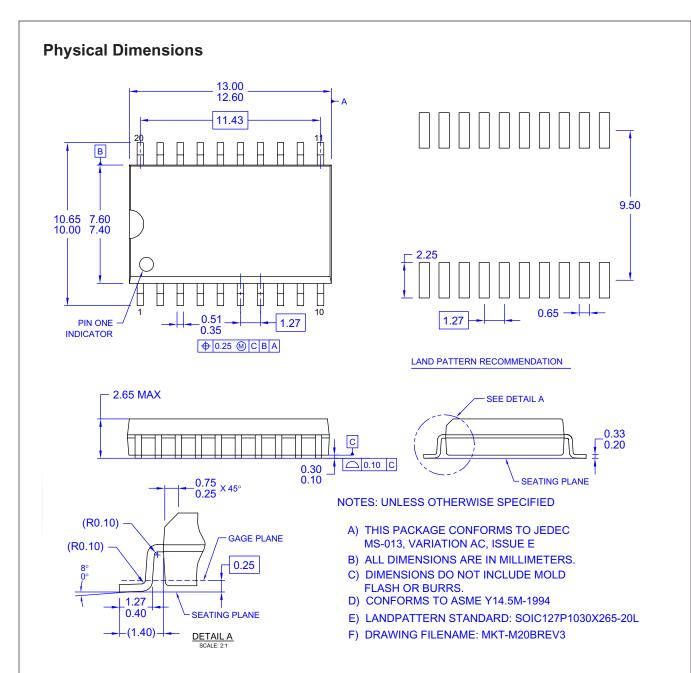
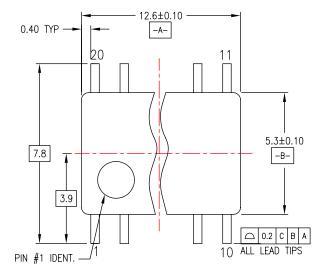
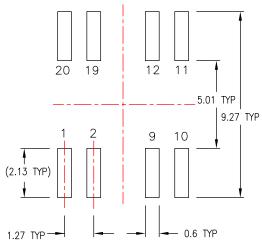


Figure 1. 20-Lead Small Outline Integrated Circuit (SOIC), JEDEC MS-013, 0.300" Wide

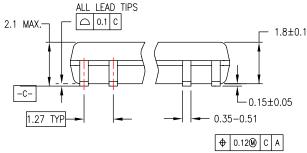
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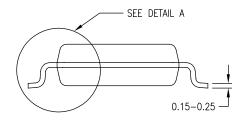
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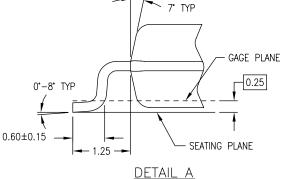




DIMENSIONS ARE IN MILLIMETERS

NOTES:

- A. CONFORMS TO EIAJ EDR-7320 REGISTRATION, ESTABLISHED IN DECEMBER, 1998.
 B. DIMENSIONS ARE IN MILLIMETERS.
 C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.



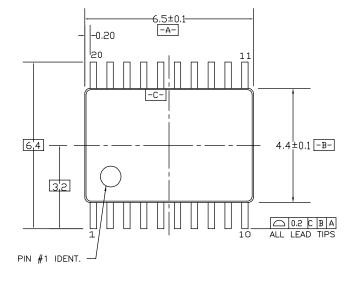
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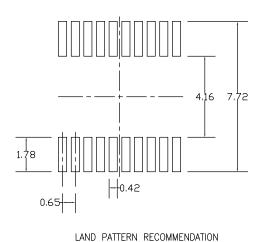
Figure 2. 20-Lead Small Outline Package (SOP), EIAJ TYPE II, 5.3mm Wide

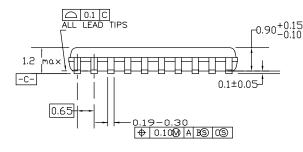
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NOTES:

- A. CONFORMS TO JEDEC REGISTRATION MD-153, VARIATION AC, REF NOTE 6, DATE $7/93.\,$
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLDS FLASH, AND TIE BAR EXTRUSIONS.
- D. DIMENSIONS AND TOLERANCES PER ANSI Y14.5M, 1982.

0.09-0.20¹ R0.09min GAGE PLANE 0 - 8*7 -0.6±0.1 R0.09min GAGE PLANE R0.09min

SEE DETAIL A

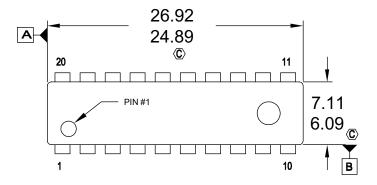
DETAIL A

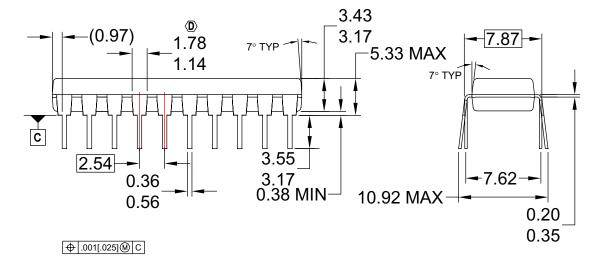
MTC20REVD1

Figure 3. 20-Lead Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

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NOTES:
A. CONFORMS TO JEDEC REGISTRATION MS-001,
VARIATIONS AD.

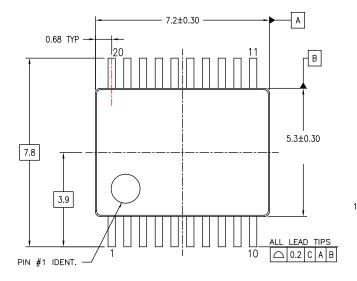
- **B. ALL DIMENSIONS ARE IN MILLIMETERS**
- © DOES NOT INCLUDE MOLD FLASH OR PROTRUSIONS.
 MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED
- 0.25MM.

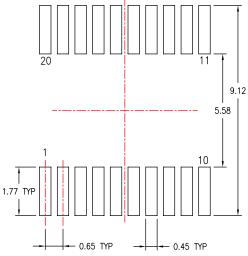
 D. DOES NOT INCLUDE DAMBAR PROTRUSIONS. DAMBAR PROTRUSIONS SHALL NOT EXCEED
- E. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994. F. DRAWING FILE NAME: N20AREV8

Figure 4. 20-Lead Plastic Dual-In-Line Package (PDIP), JEDEC MS-001, 0.300" Wide

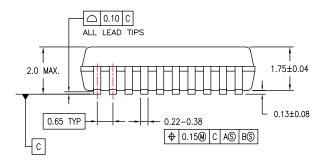
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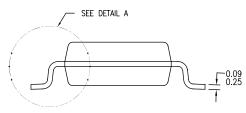
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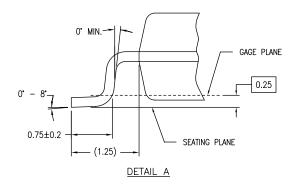




DIMENSIONS ARE IN MILLIMETERS

NOTES:

- A. CONFORMS TO JEDEC REGISTRATION MO-150, VARIATION AE, DATE 1/94.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS.
- D. DIMENSIONS AND TOLERANCES PER ASME Y14.5M 1994.



MSA20REVB

Figure 5. 20-Lead Shrink Small Outline Package (SSOP), JEDEC MO-150, 5.3mm Wide

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